

04-19-01

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THE COMMISSIONER OF PATENTS AND TRADEMARKS  
Washington, D.C. 20231

Docket No. MEG 01-004

Submitted herewith for filing is the Patent Application of:

Inventor: MOU SHIUNG LIN, MING TA LEI, CHUEN JYE LIN

For: A STRUCTURE AND MANUFACTURING METHOD OF A CHIP SCALE PACKAGE

JC986 U.S. PTO  
09/837007  
04/18/01

Enclosed are:

- ☒ 9 sheets of drawing(s) - formal.
- ☒ An assignment of the invention to MEGIC Corp.
- ☐ An associate power of attorney ☒ Applicant claims small entity status
- ☒ Request & Certification under 35 USC 122(b)(2)(b)(i)

The Filing fee has been calculated as shown below:

	(Col. 1)	(Col. 2)		SMALL ENTITY
FOR:	NO. FILED	NO. EXTRA	RATE	FEE
BASIC FEE				\$355.
TOTAL CLAIMS	24 -20=	4	x 9. =	\$36.
INDEP CLAIMS	2 -3=	0	x =	\$ 0.
MULTIPLE DEPENDENT CLAIM PRESENTED			+ 260 =	
SUB TOTAL				\$391.
ASSIGNMENT				\$40.
TOTAL				\$ 431.

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**REQUEST AND CERTIFICATION  
UNDER  
35 U.S.C. 122(b)(2)(B)(i)**

First Named Inventor

Hou Shiung Lin

Title

A Structure and Manufacturing  
Method of A Chip Scale Package

Atty Docket Number

I hereby certify that the invention disclosed in the attached application **has not and will not** be the subject of an application filed in another country, or under a multilateral agreement, that requires publication at eighteen months after filing. I hereby request that the attached application not be published under 35 U.S.C. 122(b).

4/18/01

Date

S. M. C.

Signature

Stephen B. Ackerman

Typed or printed name 37,761

This request must be signed in compliance with 37 CFR 1.33(b) and submitted with the application upon filing.

Applicant may rescind this nonpublication request at any time. If applicant rescinds a request that an application not be published under 35 U.S.C. 122(b), the application will be scheduled for publication at eighteen months from the earliest claimed filing date for which a benefit is claimed.

If applicant subsequently files an application directed to the invention disclosed in the attached application in another country, or under a multilateral international agreement, that requires publication of applications eighteen months after filing, the applicant **must** notify the United States Patent and Trademark Office of such filing within forty-five (45) days after the date of the filing of such foreign or international application. **Failure to do so will result in abandonment of this application (35 U.S.C. 122(b)(2)(B)(iii)).**

Burden Hour Statement: This collection of information is required by 37 CFR 1.213(a). The information is used by the public to request that an application not be published under 35 U.S.C. 122(b) (and the PTO to process that request). Confidentiality is governed by 35 U.S.C. 122 and 37 CFR 1.14. This form is estimated to take 6 minutes to complete. This time will vary depending upon the needs of the individual case. Any comments on the amount of time you are required to complete this form should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, Washington, DC 20231. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Assistant Commissioner for Patents, Washington, DC 20231.